

# PEMH17; PUMH17

NPN/NPN resistor-equipped transistors;  
R1 = 47 k $\Omega$ , R2 = 22 k $\Omega$

Rev. 02 — 3 May 2005

Product data sheet

## 1. Product profile

### 1.1 General description

NPN/NPN Resistor-Equipped Transistors (RET).

Table 1: Product overview

Type number	Package		NPN/PNP complement	PNP/PNP complement
	Philips	JEITA		
PEMH17	SOT666	-	PEMD17	PEMB17
PUMH17	SOT363	SC-88	PUMD17	PUMB17

### 1.2 Features

- Built-in bias resistors
- Simplifies circuit design
- Reduces component count
- Reduces pick and place costs

### 1.3 Applications

- Low current peripheral driver
- Control of IC inputs
- Replaces general-purpose transistors in digital applications

### 1.4 Quick reference data

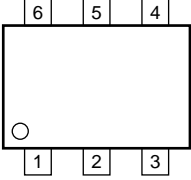
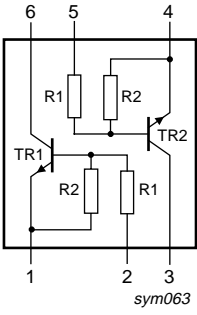
Table 2: Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>CEO</sub>	collector-emitter voltage	open base	-	-	50	V
I <sub>O</sub>	output current (DC)		-	-	100	mA
R1	bias resistor 1 (input)		33	47	61	k $\Omega$
R2/R1	bias resistor ratio		0.37	0.47	0.57	

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## 2. Pinning information

Table 3: Pinning

Pin	Description	Simplified outline	Symbol
1	GND (emitter) TR1	 001aab555	 sym063
2	input (base) TR1		
3	output (collector) TR2		
4	GND (emitter) TR2		
5	input (base) TR2		
6	output (collector) TR1		

## 3. Ordering information

Table 4: Ordering information

Type number	Package		Version
	Name	Description	
PEMH17	-	plastic surface mounted package; 6 leads	SOT666
PUMH17	SC-88	plastic surface mounted package; 6 leads	SOT363

## 4. Marking

Table 5: Marking codes

Type number	Marking code <a href="#">[1]</a>
PEMH17	5T
PUMH17	H4*

- [1] \* = -: made in Hong Kong  
 \* = p: made in Hong Kong  
 \* = t: made in Malaysia  
 \* = W: made in China

## 5. Limiting values

**Table 6: Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit	
<b>Per transistor</b>						
$V_{CBO}$	collector-base voltage	open emitter	-	50	V	
$V_{CEO}$	collector-emitter voltage	open base	-	50	V	
$V_{EBO}$	emitter-base voltage	open collector	-	10	V	
$V_I$	input voltage					
	positive		-	+40	V	
	negative		-	-10	V	
$I_O$	output current (DC)		-	100	mA	
$I_{CM}$	peak collector current		-	100	mA	
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$				
	SOT363		[1]	-	200	mW
	SOT666		[1][2]	-	200	mW
$T_{stg}$	storage temperature		-65	+150	°C	
$T_j$	junction temperature		-	150	°C	
$T_{amb}$	ambient temperature		-65	+150	°C	
<b>Per device</b>						
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$				
	SOT363		[1]	-	300	mW
	SOT666		[1][2]	-	300	mW

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

## 6. Thermal characteristics

**Table 7: Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per transistor</b>						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air				
	SOT363		[1]	-	625	K/W
	SOT666		[1][2]	-	625	K/W
<b>Per device</b>						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air				
	SOT363		[1]	-	416	K/W
	SOT666		[1][2]	-	416	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

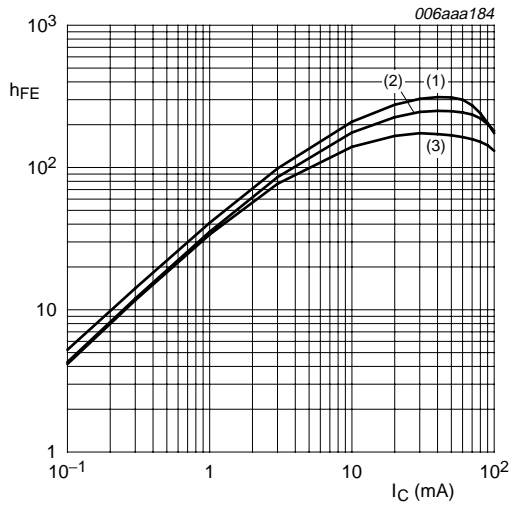
[2] Reflow soldering is the only recommended soldering method.

## 7. Characteristics

**Table 8: Characteristics**

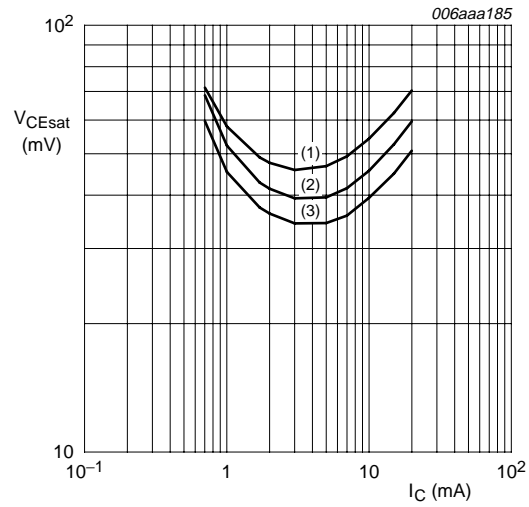
$T_{amb} = 25^\circ\text{C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per transistor</b>						
$I_{CBO}$	collector-base cut-off current	$V_{CB} = 50\text{ V}; I_E = 0\text{ A}$	-	-	100	nA
$I_{CEO}$	collector-emitter cut-off current	$V_{CE} = 30\text{ V}; I_B = 0\text{ A}$	-	-	1	$\mu\text{A}$
		$V_{CE} = 30\text{ V}; I_B = 0\text{ A}; T_j = 150^\circ\text{C}$	-	-	50	$\mu\text{A}$
$I_{EBO}$	emitter-base cut-off current	$V_{EB} = 5\text{ V}; I_C = 0\text{ A}$	-	-	110	$\mu\text{A}$
$h_{FE}$	DC current gain	$V_{CE} = 5\text{ V}; I_C = 5\text{ mA}$	60	-	-	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = 10\text{ mA}; I_B = 0.5\text{ mA}$	-	-	150	mV
$V_{I(off)}$	off-state input voltage	$V_{CE} = 5\text{ V}; I_C = 100\text{ }\mu\text{A}$	-	1.7	1.2	V
$V_{I(on)}$	on-state input voltage	$V_{CE} = 0.3\text{ V}; I_C = 2\text{ mA}$	4	2.7	-	V
R1	bias resistor 1 (input)		33	47	61	k $\Omega$
R2/R1	bias resistor ratio		0.37	0.47	0.57	
$C_c$	collector capacitance	$V_{CB} = 10\text{ V}; I_E = i_e = 0\text{ A}; f = 1\text{ MHz}$	-	-	2.5	pF



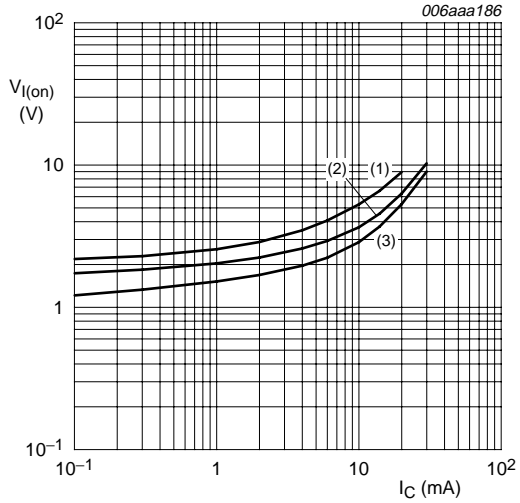
$V_{CE} = 5\text{ V}$   
 (1)  $T_{amb} = 100\text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25\text{ }^\circ\text{C}$   
 (3)  $T_{amb} = -40\text{ }^\circ\text{C}$

**Fig 1. DC current gain as a function of collector current; typical values**



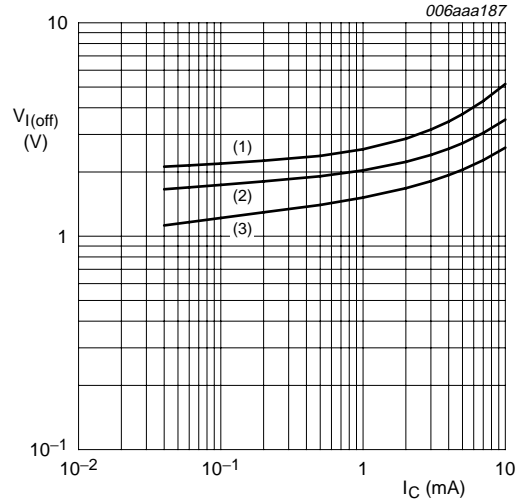
$I_C/I_B = 20$   
 (1)  $T_{amb} = 100\text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25\text{ }^\circ\text{C}$   
 (3)  $T_{amb} = -40\text{ }^\circ\text{C}$

**Fig 2. Collector-emitter saturation voltage as a function of collector current; typical values**



$V_{CE} = 0.3\text{ V}$   
 (1)  $T_{amb} = -40\text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25\text{ }^\circ\text{C}$   
 (3)  $T_{amb} = 100\text{ }^\circ\text{C}$

**Fig 3. On-state input voltage as a function of collector current; typical values**



$V_{CE} = 5\text{ V}$   
 (1)  $T_{amb} = -40\text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25\text{ }^\circ\text{C}$   
 (3)  $T_{amb} = 100\text{ }^\circ\text{C}$

**Fig 4. Off-state input voltage as a function of collector current; typical values**

## 8. Package outline

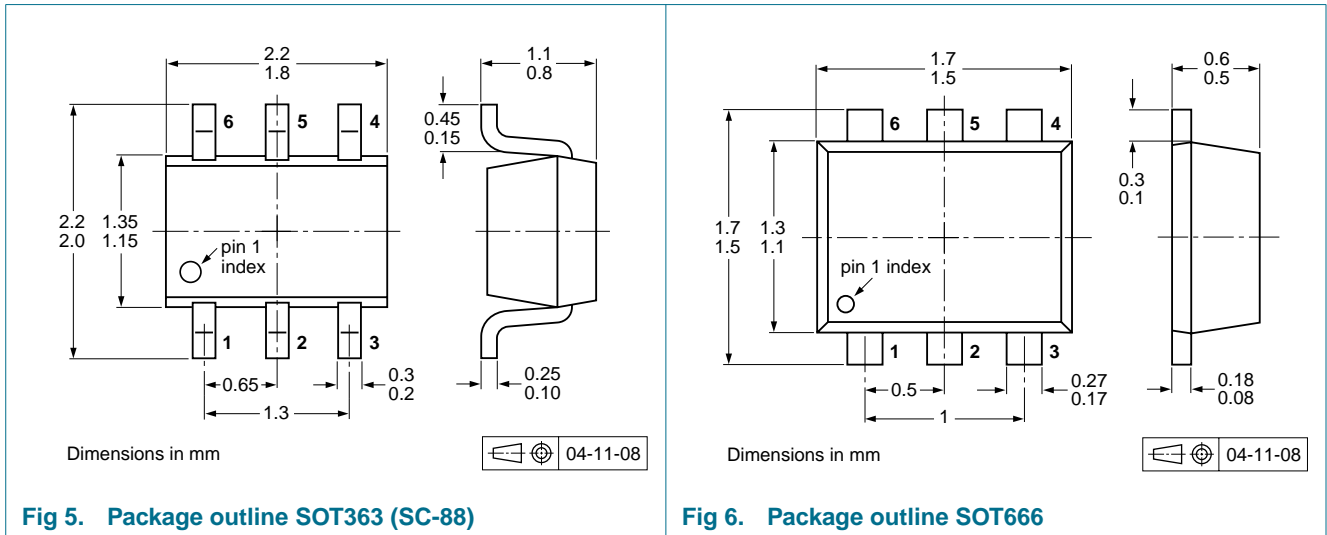


Fig 5. Package outline SOT363 (SC-88)

Fig 6. Package outline SOT666

## 9. Packing information

Table 9: Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code. [1]

Type number	Package	Description	Packing quantity			
			3000	4000	8000	10000
PEMH17	SOT666	2 mm pitch, 8 mm tape and reel	-	-	-315	-
		4 mm pitch, 8 mm tape and reel	-	-115	-	-
PUMH17	SOT363	4 mm pitch, 8 mm tape and reel; T1 [2]	-115	-	-	-135
		4 mm pitch, 8 mm tape and reel; T2 [3]	-125	-	-	-165

[1] For further information and the availability of packing methods, see Section 15.

[2] T1: normal taping

[3] T2: reverse taping

## 10. Revision history

Table 10: Revision history

Document ID	Release date	Data sheet status	Change notice	Doc. number	Supersedes
PEMH17_PUMH17_2	20050503	Product data sheet	-	9397 750 14461	PUMH17_1
Modifications:		<ul style="list-style-type: none"> <li>The format of this data sheet has been redesigned to comply with the new presentation and information standard of Philips Semiconductors.</li> <li>Type PEMH17 added</li> <li><a href="#">Table 8 "Characteristics"</a>: <math>V_{i(on)}</math> redefined to <math>V_{I(on)}</math> on-state input voltage</li> <li><a href="#">Table 8 "Characteristics"</a> <math>V_{i(off)}</math> redefined to <math>V_{I(off)}</math> off-state input voltage</li> <li><a href="#">Figure 1, 2, 3 and 4</a>: electrical graphs added</li> <li><a href="#">Section 9 "Packing information"</a>: added</li> <li><a href="#">Section 14 "Trademarks"</a>: added</li> </ul>			
PUMH17_1	20031009	Product specification	-	9397 750 11888	-

## 11. Data sheet status

Level	Data sheet status <sup>[1]</sup>	Product status <sup>[2] [3]</sup>	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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